

PMP10654 REV 3 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		PMP10654	Any	Printed Circuit Board	
2	C1, C2, C10, C11	4	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22uF, 25V, +/-10%, X7R, 1210	1210
3	C3, C9	2	0.01uF	C1608X7R1H103K	TDK	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603
4	C4, C5	2	10uF	C3216X7R1E106M160AE	TDK	CAP, CERM, 10 uF, 25 V, +/- 20%, X7R, 1206_190	1206_190
5	C6	1	4.7uF	GRM31CR71H475KA12L	MuRata	CAP, CERM, 4.7 uF, 50 V, +/- 10%, X7R, 1206	1206
6	C7	1	0.1uF	C1608X7R1H104K	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
7	C8	1	1uF	C1608X7R1E105K080AB	TDK	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603
8	C12	1	100pF	GRM42A7U3F101JW31L	MuRata	CAP, CERM, 100 pF, 3150 V, +/- 5%, U2J, 1808	1808
9	Cac	1	1000pF	C1608X7R1H102K	TDK	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	0603
10	Cr	1	0.01uF	GRM188R71H103KA01D	MuRata	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603
11	D1, D2	2	60V	RB160M-60TR	Rohm	Diode, Schottky, 60 V, 1 A, SOD-123	SOD-123
12	J1, J2, J3, J4	4		HTSW-102-07-G-S	Samtec	Header, 100mil, 2x1, Gold, TH	Header, 100mil, 2x1, TH
13	R1	1	4.02k	CRCW06034K02FKEA	Vishay-Dale	RES, 4.02 k, 1%, 0.1 W, 0603	0603
14	R2	1	2.00k	CRCW06032K00FKEA	Vishay-Dale	RES, 2.00 k, 1%, 0.1 W, 0603	0603
15	R3	1	680k	RC0603FR-07680KL	Yageo America	RES, 680 k, 1%, 0.1 W, 0603	0603
16	R4	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100k ohm, 1%, 0.1W, 0603	0603
17	R5	1	18.7k	CRCW060318K7FKEA	Vishay-Dale	RES, 18.7 k, 1%, 0.1 W, 0603	0603
18	Rfbb, Rr	2	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0 k, 1%, 0.1 W, 0603	0603
19	Rfbt	1	133k	CRCW0603133KFKEA	Vishay-Dale	RES, 133 k, 1%, 0.1 W, 0603	0603
20	T1	1	25uH	750315445	Würth Elektronik	Transformer, 25uH, 10-pin, Thru-Hole, 1:1:0.6	Würth EPC13, 10-pin, THT, Horizontal
21	U1	1		LM5160ADNTR	Texas Instruments	Wide Input 65V, 1.5A Synchronous Step-Down DC-DC Converter, DNT0012B	DNT0012B

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